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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Fuseholder Open Design, 5 x 20 mm, SMD, var. Covers, IEC 60335-1



OGN-SMD



OGN-SMD for increased solder temperature with gold contacts



OGN-SMD equipped with cover (available separately)

250 VAC · 4 W/10 A (VDE) · 500 V · 10 A (UL/CSA)



Description

- For appliances in unattended use
- Glow wire tests acc. to IEC 60695-2-12 and -13

Unique Selling Proposition

- Suitable for fully automated PCD assembling
- Available with blister tape packaging
- Small design height
- Available preassembled with fuses

Standards

- IEC 60127-6
- UL 4248-1
- CSA C22.2 no. 4248.1

Approvals

- VDE Certificate Number: 40001042
- UL File Number: E39328

Applications

- Household appliances


References

[Packaging Details](#)

Weblinks

[pdf datasheet](#), [html-datasheet](#), [General Product Information](#), [Packaging details](#), [Approvals](#), [CE declaration of conformity](#), [RoHS](#), [CHINA-RoHS](#), [REACH](#), [Distributor-Stock-Check](#), [Accessories](#), [Detailed request for product](#)

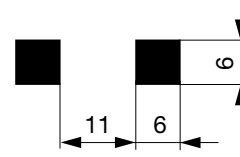
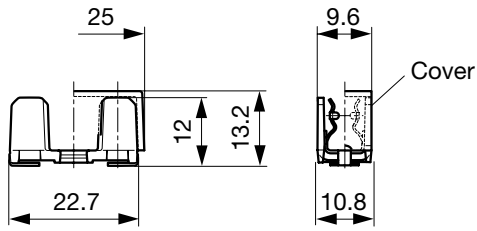
Technical Data

Fuse-Link	5 x 20 mm
Mounting	PCB
Terminal	Solder SMT
Rated Voltage	250 VAC (VDE), 500 V (UL/CSA)
Rated current	10 A (VDE), 10 A (UL/CSA)
Rated Power Acceptance IEC	4 W / 10 A @ Ta 23 °C 2.5 W / 10 A with transparent cover, see derating curves
Degree of Protection	IP 20 (with cover)
Protection Class	Suitable for appliances with protection class I or II acc. to IEC 61140
Admissible Ambient Air Temp.	-40 °C to 85 °C
Climatic Category	40/085/21 acc. to IEC 60068-1
Material: Socket	see variants
Material: Cover	Thermoplastic UL 94V-0
Material: Terminals	Tin-Plated Copper Alloy
Unit Weight	1.7 g
Storage Conditions	0 °C to 60 °C, max. 70% r.h.
Product Marking	 , Type, Rated Voltage, Rated current, Power Rating, Approvals

Soldering Methods	Reflow (lead-free) Soldering Profile
Solderability	245-260 °C / max. 30 sec acc. to JE-DEC J-STD-020D
Contact Resistance	≤ 10 mΩ at 20 mV acc. to IEC 60127-6
Dielectric Strength	> 3 kV between Life parts (50 Hz; 1 min)
Impulse Withstand Voltage	> 4 kV between Life parts
Insulation Resistance	≥ 10 MΩ (500 VDC; 1 min)
Overvoltage Category	III acc. to IEC 60664-1
Pollution Degree	3 acc. to IEC 60664-1

Detailed information on product approvals, code requirements, usage instructions and detailed test conditions can be looked up in [General Product Information](#)

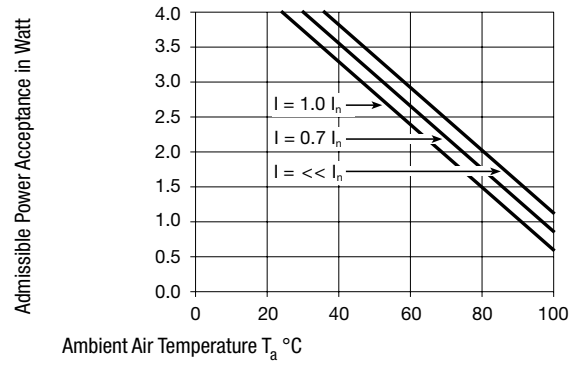
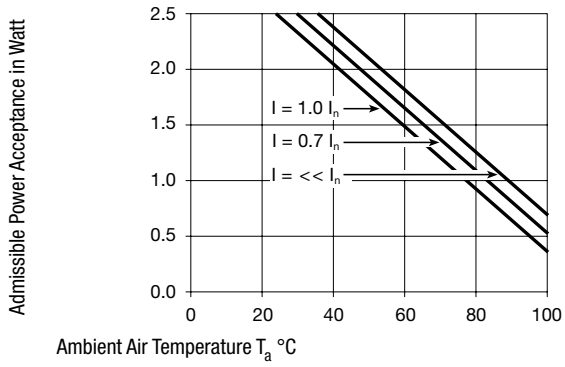
Dimension



Soldering pads

Derating Curves

With Transparent Cover



Order numbers for pre-assembled OGN-SMD, blister tape packaging with 400 pieces per reel

Rated current In	FTT 5x20 with reflow cover 0853.0571	FTT 5x20 no cover	FST 5x20 with reflow cover 0853.0571	FST 5x20 no cover	FSF 5x20 with reflow cover 0853.0571	FSF 5x20 no cover	SMD-SPT 5x20 with reflow cover 0853.0571	SMD-SPT 5x20 no cover
50 mA			0031.8304	0031.8354				
63 mA	0031.8501	0031.8551	0031.8305	0031.8355				
80 mA	0031.8502	0031.8552	0031.8306	0031.8356				
100 mA	0031.8503	0031.8553	0031.8307	0031.8357				
125 mA	0031.8504	0031.8554	0031.8308	0031.8358				
160 mA	0031.8505	0031.8555	0031.8309	0031.8359				
200 mA	0031.8506	0031.8556	0031.8310	0031.8360				
250 mA	0031.8507	0031.8557	0031.8311	0031.8361				
315 mA	0031.8508	0031.8558	0031.8312	0031.8362				
400 mA	0031.8509	0031.8559	0031.8313	0031.8363				
500 mA	0031.8510	0031.8560	0031.8314	0031.8364	0031.8413	0031.8463		
630 mA	0031.8511	0031.8561	0031.8315	0031.8365	0031.8414	0031.8464		
800 mA	0031.8512	0031.8562	0031.8316	0031.8366	0031.8415	0031.8465		
1 A	0031.8513	0031.8563	0031.8317	0031.8367	0031.8416	0031.8466	0031.8993	0031.9007
1,25 A	0031.8514	0031.8564	0031.8318	0031.8368	0031.8417	0031.8467	0031.8994	0031.9008
1,6 A	0031.8515	0031.8565	0031.8319	0031.8369	0031.8418	0031.8468	0031.8995	0031.9009
2A	0031.8516	0031.8566	0031.8320	0031.8370	0031.8419	0031.8469	0031.8996	0031.9010
2,5 A	0031.8517	0031.8567	0031.8321	0031.8371	0031.8420	0031.8470	0031.8997	0031.9011
3,15 A	0031.8518	0031.8568	0031.8322	0031.8372	0031.8421	0031.8471	0031.8998	0031.9012
4 A	0031.8519	0031.8569	0031.8323	0031.8373	0031.8422	0031.8472	0031.8999	0031.9013
5 A			0031.8324	0031.8374	0031.8423	0031.8473	0031.9000	0031.9014
6,3 A			0031.8325	0031.8375	0031.8424	0031.8474	0031.9001	0031.9015
8 A			0031.8326	0031.8376	0031.8425	0031.8475	0031.9002	0031.9016
10 A			0031.8327	0031.8377	0031.8426	0031.8476	0031.9003	0031.9017

All fuses in the pre-assembled OGN-SMD fuseholders are suitable for the reflow solder process.

All Variants

Holder	Material	Material: Terminals	Reflow Condition	Packaging	Order Number
●	Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=245 +/-5 °C, tp = max. 30 s	Bulk 128 x 91 x 60 mm (100 pcs.)	0031.8221
●	Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=245 +/-5 °C, tp = max. 30 s	Blister Tape 38 cm Reel (400 pcs.)	0031.8225
●	Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=245 +/-5 °C, tp = max. 30 s	Blister Tray 266 x 174 mm (500 pcs.)	0031.8222
●	Spec. Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=260 +/-5 °C, tp = max. 30 s	Bulk 128 x 91 x 60 mm (100 pcs.)	0031.8263
●	Spec. Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=260 +/-5 °C, tp = max. 30 s	Blister Tape 38 cm Reel (400 pcs.)	0031.8265
●	Spec. Thermoplastic	Tin-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=260 +/-5 °C, tp = max. 30 s	Blister Tray 266 x 174 mm (500 pcs.)	0031.8264
●	Spec. Thermoplastic	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=260 +/-5 °C, tp = max. 30 s	Bulk 128 x 91 x 60 mm (100 pcs.)	0031.8273
●	Spec. Thermoplastic	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=260 +/-5 °C, tp = max. 30 s	Blister Tape 38 cm Reel (400 pcs.)	0031.8275
●	Spec. Thermoplastic	Gold-Plated Copper Alloy	acc. to JEDEC J-STD-020D, Tp=260 +/-5 °C, tp = max. 30 s	Blister Tray 266 x 174 mm (500 pcs.)	0031.8274

Most Popular.

Availability for all products can be searched real-time:<http://www.schurter.com/en/Stock-Check/Stock-Check-SCHURTER>

The fuseholder is suitable for use in equipment according to IEC 60335-1.

Fuseholders with gold-plated terminals are more heat resistant than fuseholders with tin-plated terminals.

If soldering problems occur with the thermoplastic version, it is recommended to use the spec. thermoplastic with tin-plated and gold-plated terminals.

Packaging Unit see variants

Accessories

Description



Covers for OGN, OGN-SMD
Cover for Holder OGN, OGN-SMD



Adapter to OGN, OGN-SMD
Fuse Carriage with Handle for OGN, OGN-SMD